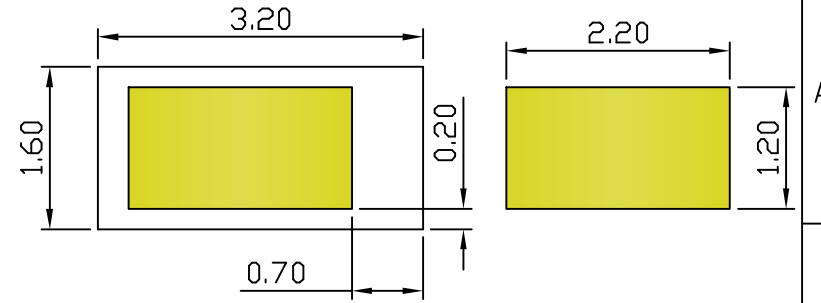
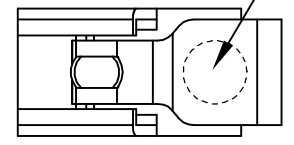


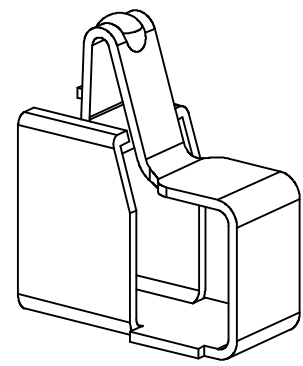
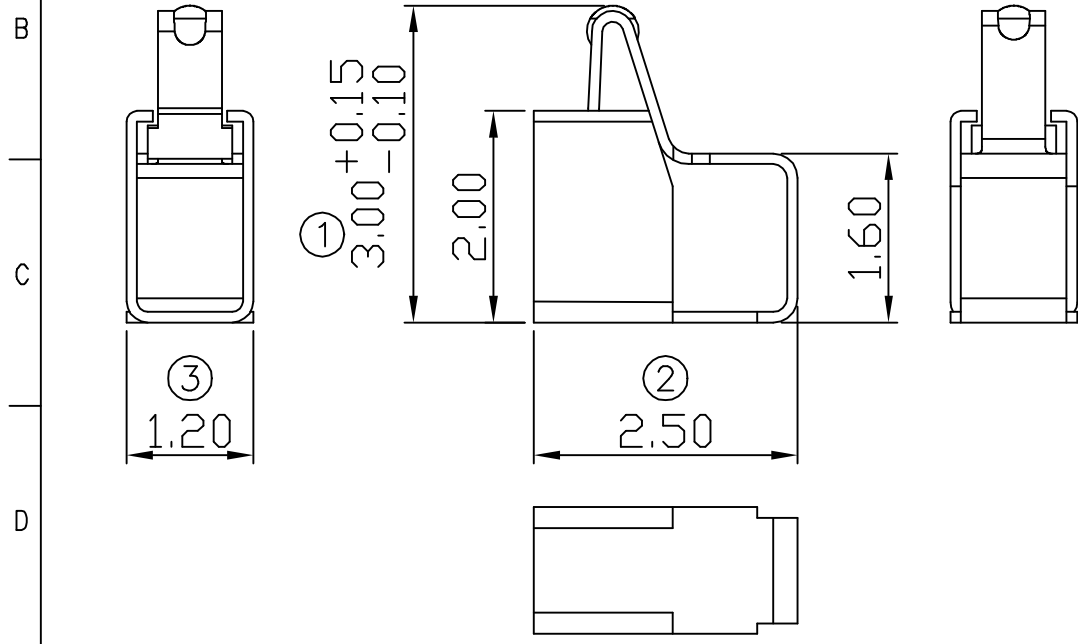
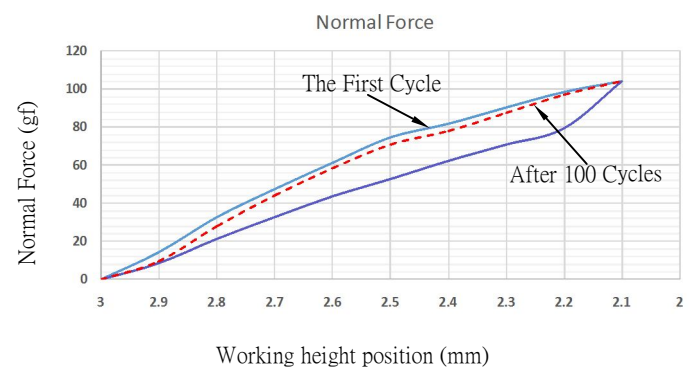


Place Area Nozzle



RECOMMENDED SOLDERING PCB LAYOUT

TOLERANCE(.XX±0.05)



- Note:
1. Material: Titanium copper Thickness 0.10mm
 2. Electroplate:
 - Au >1u" on contact area
 - Gold Flash on solder area
 - Nickel underplating over all
 3. Electrical Characteristics:
 - 3-1 Current Voltage: 12V
 - 3-2 Current Rate: 3A
 - 3-3 Contact Resistance: Normal Compression < 30mΩ
 4. Working Height of Application: 2.10~2.60 mm
 5. Spring Force Tolerance is ±20gf
 6. Operating Temperature: -20℃~+85℃

00	08/16-'19	Design creation								
REV	Date	Description								
DRAFT	Hardy Hsieh	DATE	08/16-'19	RoHS Compatible						
CHECKER	Justin Wu	DATE	08/16-'19							
APPROVAL	Timothy Chen	DATE	08/16-'19			SHEET	1-2	SCALE	Not to scale	UNIT

TOLERANCE/CLASS			
RANGE(mm)	1	2	3
≤30	±0.10	0.15	0.20
30<~≤120	±0.15	0.20	0.30
120<~≤300	±0.20	0.30	0.50
300<	±0.30	0.50	0.80
ANGLES	±2.5°		

EMI STOP CORP.

EMISTOP QTT-30Q1G CUS P/N